

REMARKS

On page 3 of the Office Action, 2nd paragraph, the Examiner refers to “Okami” and makes the same reference at page 4, last paragraph. The rejection on page 3, 1st paragraph, does not refer to Okami but to Takamura et al. Applicants wish to thank Examiner Zimmer for the informal discussion in which he indicated that this is merely a typographical error and his arguments should have referred to Takamura et al.

Claims 1-11 and 13-19 are active in this application.

The present invention as set forth in **Claim 1** relates to a heat conductive silicone rubber composite sheet, comprising:

a laminated structure with an intermediate layer and a pair of outer layers laminated to both surfaces of said intermediate layer, wherein

(A) said intermediate layer is a layer of a synthetic resin film that displays heat resistance and electrical insulation, and

(B) said outer layers are silicone rubber layers formed by curing a composition comprising (a) an organopolysiloxane, (b) a curing agent, (c) a heat conductive filler, and (d) a silicon compound-based adhesion imparting agent with at least one functional group selected from the group consisting of epoxy groups, alkoxy groups, vinyl groups, and the group represented by the formula Si—H;

wherein said curing agent of said component (b) is an organic peroxide.

The Examiner has rejected the claims over JP 2001-018330 (Takamura et al) in view of US 5,652,290 (Nakamura et al) or US 5,021,494 (Toya et al). This rejection is traversed.

US 6,379,806 corresponds to JP 2001-018330. Thus, the following discussion also refers to paragraphs of the US patent.

JP 2001-018330 discloses a composite sheet comprising a silicone rubber and a heat-resistant resin film provided on at least one side of the silicone rubber sheet (US ‘806, col. 2,

lines 48-52, 66, 67). The heat-resistant resin film can also be provided on both sides of the silicone rubber sheet (US '806, col. 6, lines 44-47 and paragraph 27 of JP 2001-018330). In other words, in this embodiment, the outer layers are heat-resistant resin and the intermediate layer is silicone rubber. However, in the present invention, the intermediate layer is a synthetic resin film and the outer layers are silicone rubber.

Takamura et al. is entirely silent about the heat conductive silicone rubber composite sheet of the present application, wherein the intermediate layer is a synthetic resin film and the outer layers are silicone rubber. Nakamura et al. (US Patent 5,652,290) and Toya et al. (US Patent 5,021,494) are also silent about the heat conductive silicone rubber composite sheet of the present application. Therefore, the inventions of the claims would not have been obvious over Takamura et al. in view of Nakamura et al. or Toya et al.

Therefore, the rejection of Claims 1-8 and 13-19 under 35 U.S.C. § 103(a) over Takamura et al in view of Nakamura et al or Toya et al is believed to be unsustainable as the present invention is neither anticipated nor obvious and withdrawal of this rejection is respectfully requested.

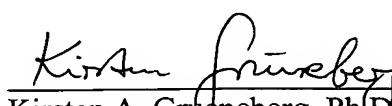
This application presents allowable subject matter, and the Examiner is kindly requested to pass it to issue. Should the Examiner have any questions regarding the claims or otherwise wish to discuss this case, he is kindly invited to contact Applicants' below-signed representative, who would be happy to provide any assistance deemed necessary in speeding this application to allowance.

Respectfully submitted,

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